Title (en)
METHOD FOR PRODUCING COPPER ALLOY MATERIAL FOR ELECTRICAL / ELECTRONIC COMPONENT

Title (de)
VERFAHREN ZUR HERSTELLUNG VON KUPFERLEGIERUNGSMATERIAL FÜR ELEKTRISCHE / ELEKTRONISCHE BAUTEILE

Title (fr)
procédé de fabrication d'un MATIÈRE D'ALLIAGE DE CUIVRE POUR UN COMPOSANT ÉLECTRIQUE/ÉLECTRONIQUE

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Application
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Abstract (en)
A copper alloy material for electrical/electronic components containing Co and Si as additional elements, wherein a compound A composed of Co and Si and having an average particle diameter of not less than 5 nm but less than 50 nm is dispersed, and at least one compound selected from the group consisting of a compound B containing one or neither of Co and Si and having an average particle diameter of not less than 50 nm but not more than 500 nm, a compound C containing both of Co and Si and an additional element and having an average particle diameter of not less than 50 nm but not more than 500 nm, and a compound D composed of Co and Si and having an average particle diameter of not less than 50 nm but not more than 500 nm, is also dispersed. The copper alloy material for electrical/electronic components is also characterized in that the matrix copper alloy has a crystal grain size of 3-35 [mu]m, and that the copper alloy material has a conductivity of not less than 50% IACS.

IPC 8 full level
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